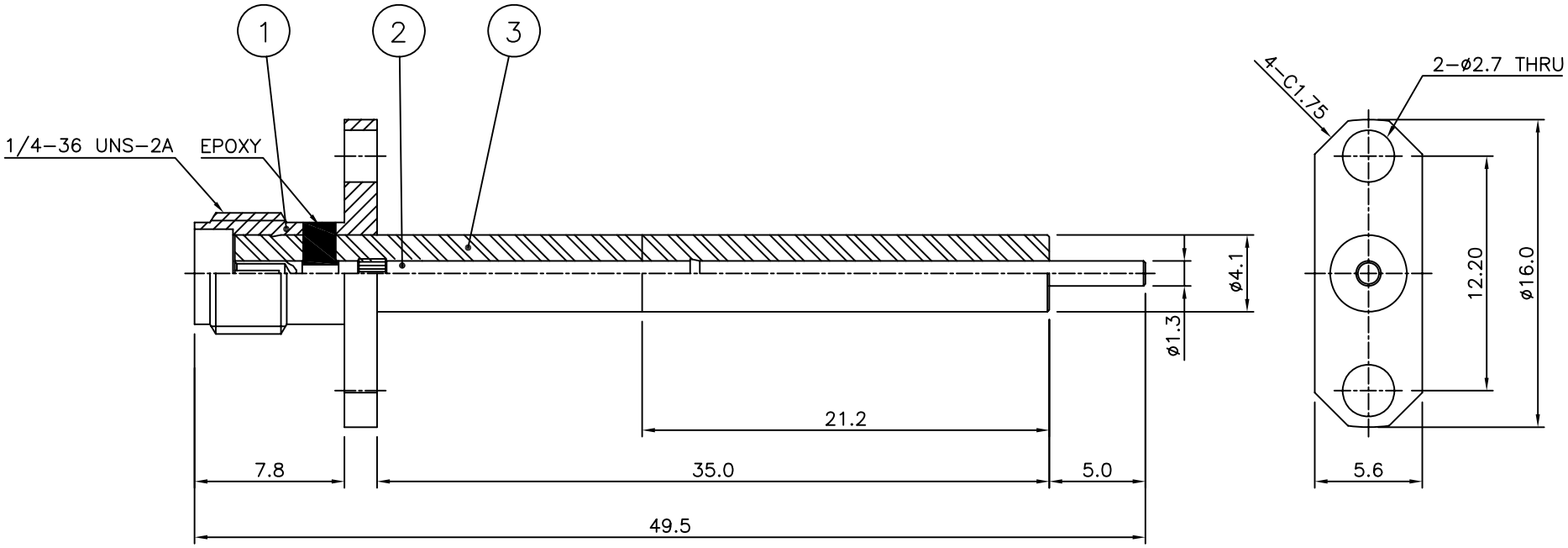
REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	C.K.KIM	I.C.KIM	2016.10.24.



조립순서 및 방법

1. ①번 BODY에 ③번 절연체(1)를 조립한다.
2. 절연체 조립후 ⌀1.7 드릴 관통시킨다. - *BURR 제거 할 것.
3. ②번 PIN을 BODY에 조립 후 ③번 절연체(2)를 PIN에 조립한다.
4. EPOXY작업을 한다.

NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE
3	INSULATOR	2	TEFLON		DIN02634-N/1
2	CONTACT	1	BeCu C17300	Gold Plate	DCT03771-5/1
1	BODY	1	MBsBD C3604BD-F	Gold Plate	DBD02962-5/2

TOLERANCE	Decimal ±0.1	DATE	2016. 10. 24.
	Angle ±1°	APPROVED BY	I.C.KIM
		CHECKED BY	
MATERIAL		DRAWN BY	C.K.KIM
FINISH		SCALE 3/1	UNIT mm

KJ COMTECH
KJ COMTECH CO.,LTD.
RF & MICROWAVE TECHNOLOGY
Tel : 82-32-347-8015
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TITLE: SMA50 SOLDER END JS-2H

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